

David Padgett Director of Technology



# Automated Tooling Design

for PCB Dispensing Application

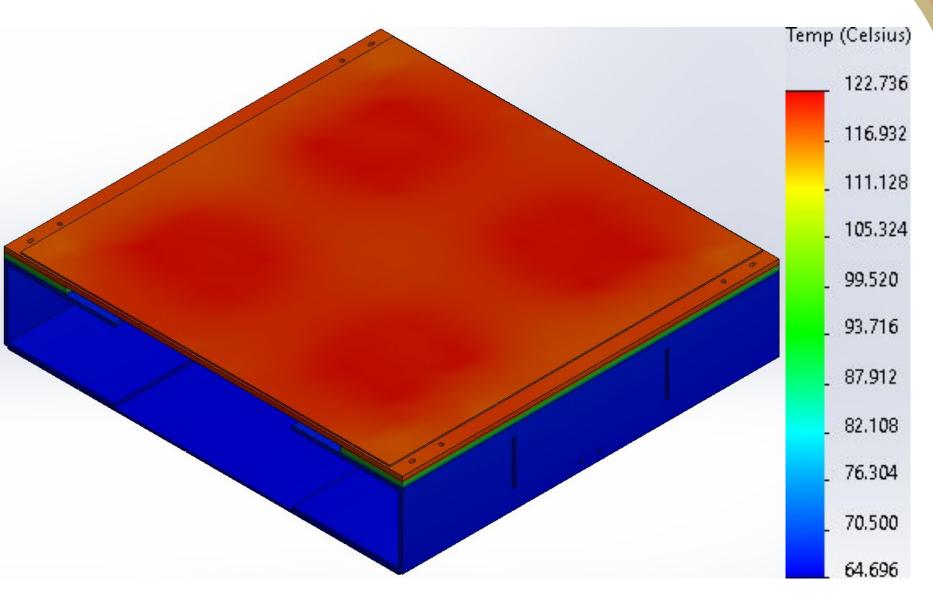
SDSU San Diego State University

Dr. Scott Shaffar College of Engineering

# **Engineering Analysis**

#### **Heating Analysis:**

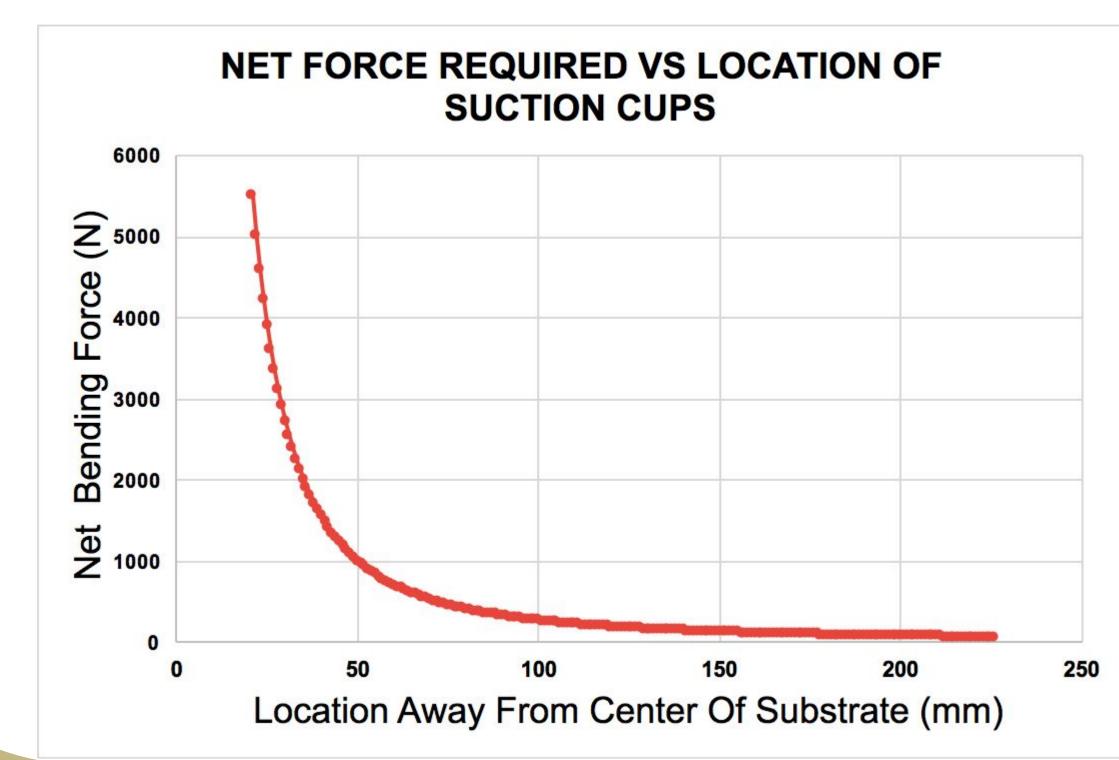
Evenly distributed
 heating element to
 heat the PCB to a
 target temperature
 of 120°C prior to
 dispensing



#### Flattening Analysis

• The force required to flatten the PCB determined the size F(x) = 2 and location of the suctions cups

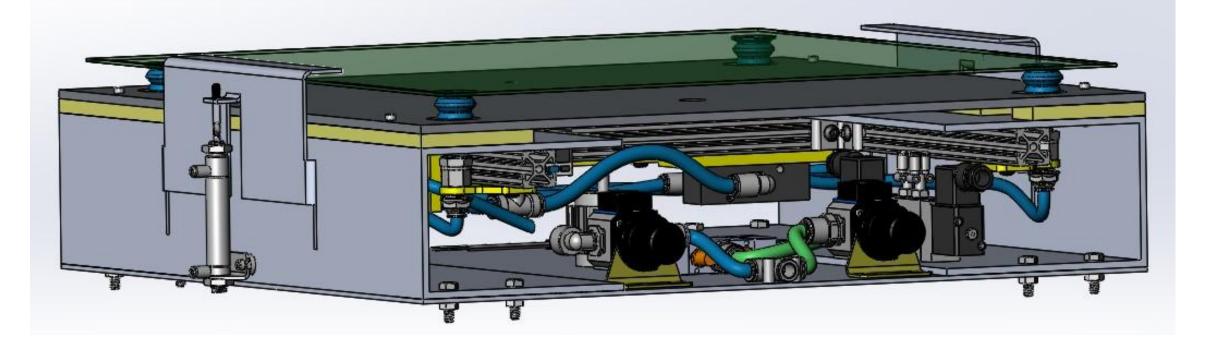
$$F(x) = 2 \cdot \left(\frac{\delta_{max}(6EI)}{x^2(3L-x)}\right)$$



#### **Project Overview**

Nordson Asymtek is sponsoring this project to develop a fully automated tooling aid to work in unison with their *Vantage* machine for a Printed Circuit Board (PCB) dispensing application. The tooling aid, placed inside the *Vantage*, must provide an automated loading, flattening, heating, moving, and unloading mechanism for the PCB with a user interface displaying the current stage of the process.

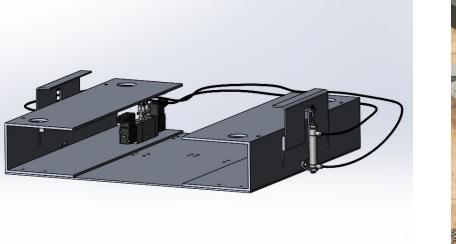
### Final Product





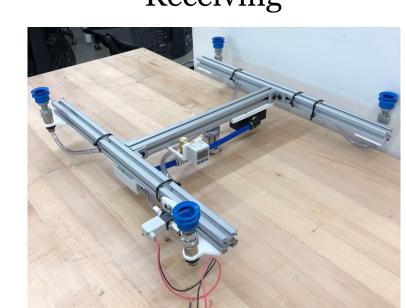
The *Vantage* acts as the power and air source. An Arduino Due, a microcontroller board, manages the inputs and outputs of each subsystem monitored by a user interface (left).

# Subsystems



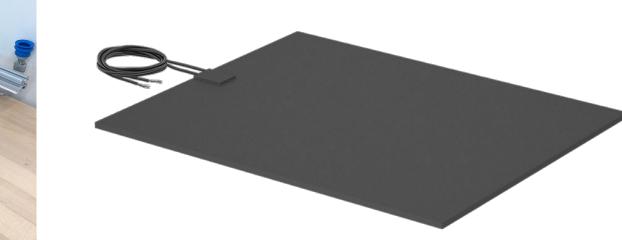


Receiving



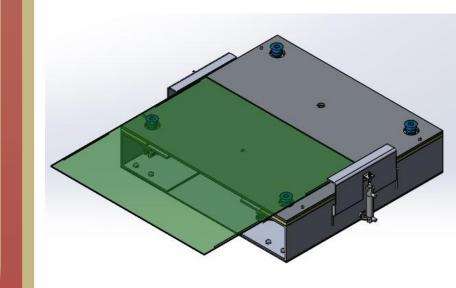
Suction

Movement

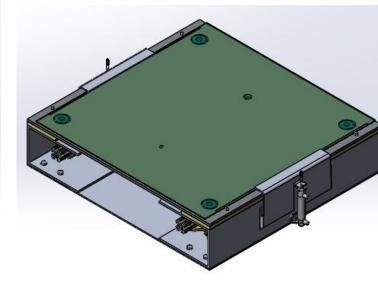


Heating

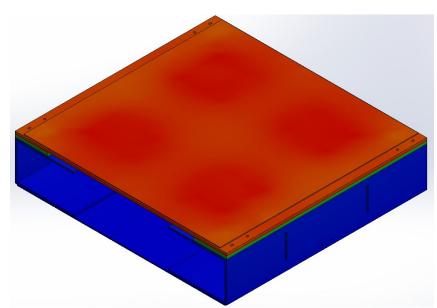
#### **Process Overview**



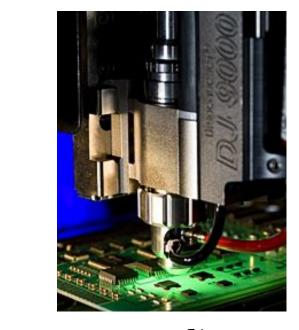
1. PCB is loaded onto the fixture from Equipment Front End Module



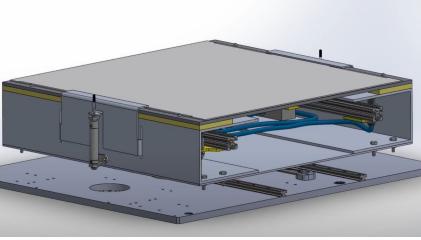
2. PCB is flattened through suction cups and clamps



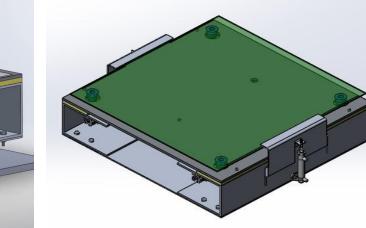
3. Heat PCB



4. *Vantage* dispenses adhesive onto PCB



5. Transport fixture to second position and dispense adhesive



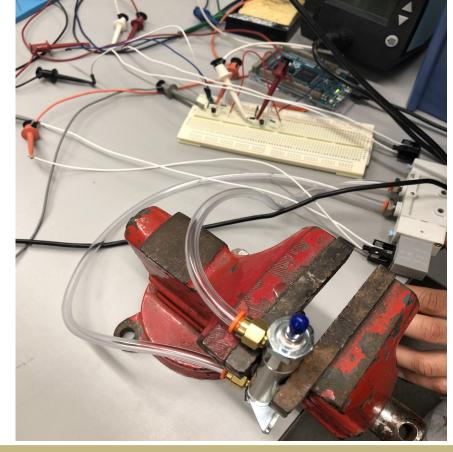
t fixture to
sition and
adhesive

6. Return to original
position, stop heating,
release suction and
clamps

\*Entire process occurs inside Nordon's *Vantage* Machine

## **Testing**





Verification testing was conducted on each subsystem to confirm specified design outputs met design input requirements. These critical specifications control flatness, temperature, and positioning.

## Design Team



Top (Left to Right):
Abdullah Alani, Jose Hernandez,
Eric Galvan, Zachary Chow
Bottom (Left to Right):
Aziz Hanna, Chad Bicoy (TL), May
Aldhaiea (TL), Shervin Shabanpour,
Denver Chan, Abdallah Alhajeri

TL = Team Lead

#### Acknowledgements

#### San Diego State University

Dr. Scott Shaffar Dr. Barry Dorr Dr. Sridhar Seshagiri

#### Nordson Asymtek

David Padgett Alon Dagan